

3.2mmx1.6mm SMD CHIP LED LAMP

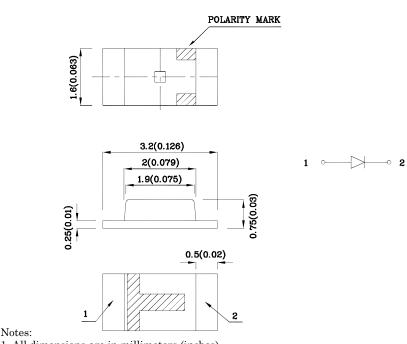
# Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- $\bullet$  RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



1. All dimensions are in millimeters (inches).

**Package Schematics** 

2. Tolerance is  $\pm 0.2(0.008")$  unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		DGK (InGaN)	Unit	
Reverse Voltage		5	V	
Forward Current	$\mathbf{I}_{\mathrm{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	PD	102.5	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$\text{-}40 \sim \text{+}85$	-0	
Electrostatic Discharge Threshold (HBM)		450	V	

Operating Characteristics (T <sub>A</sub> =25°C)		DGK (InGaN)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\rm F}$	3.3	V	
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	4.1	V	
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_{R}$	50	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λP	515*	nm	
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λD	525*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$ riangle\lambda$	35	nm	
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	45	$_{\rm pF}$	

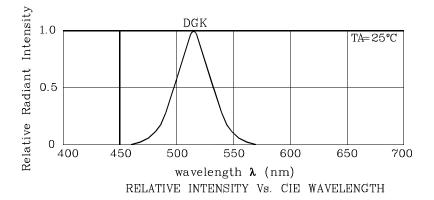
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =20mA) mcd		Wavelength CIE127-2007* λP nm	Viewing Angle 20 1/2
				min.	typ.		
ZDGK55W-1	Green	InGaN	Water Clear	200*	347*	515*	120°

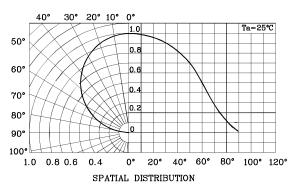
 ${\rm *Luminous\ intensity\ value\ and\ wavelength\ are\ in\ accordance\ with\ CIE127-2007\ standards.}$ 

Feb 14,2014

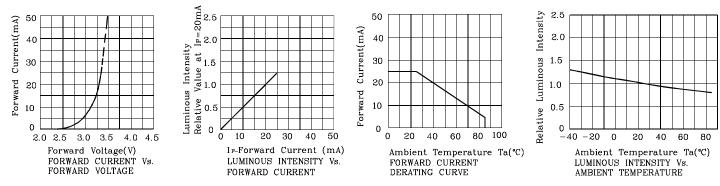
SDSA9332 V1-Z Layout: Maggie L.



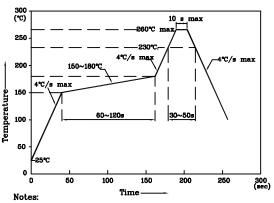




♦ DGK



# LED is recommended for reflow soldering and soldering profile is shown below.



Reflow Soldering Profile for SMD Products (Pb-Free Components)

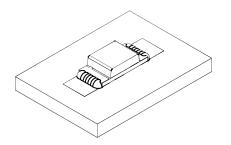
1. Maximum soldering temperature should not exceed 260°C 2. Recommended reflow temperature: 145°C-260°C

3. Do not put stress to the epoxy resin during

high temperatures conditions



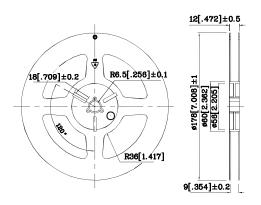
The device has a single mounting surface. The device must be mounted according to the specifications.



Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

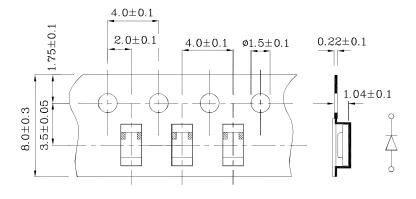


Reel Dimension



### Tape Specification (Units : mm)





Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

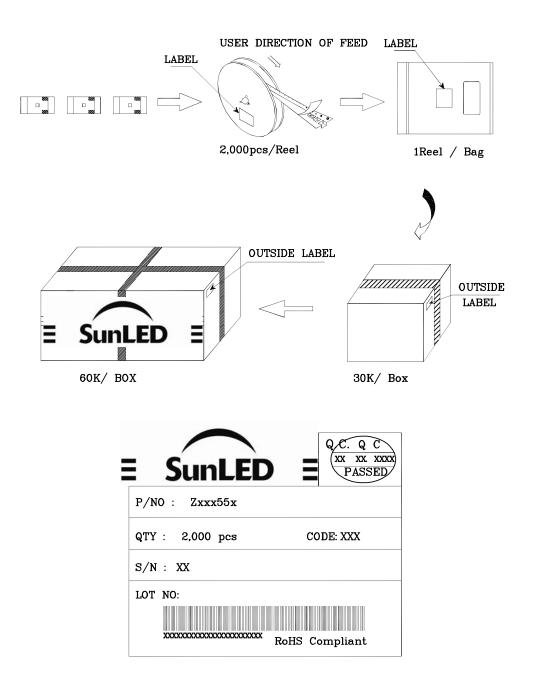
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V  $\,$ 

Note: Accuracy may depend on the sorting parameters.



# PACKING & LABEL SPECIFICATIONS



#### TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLED.com/TechnicalNotes

Feb 14,2014